

Call for Papers



International Test Conference • The Cornerstone of Test Week™

November 2-4, 2010
Test Week™: Oct 31 – Nov 5, 2010

Austin Convention Center
Austin, Texas, USA

June 1 Update: The Call for Papers completed in March, the review cycle is complete and selection of papers is underway. This update refers to the Poster Session and Panel Submissions.

International Test Conference is the world's premier conference dedicated to the electronic test of devices, boards and systems—covering the complete cycle from design verification, design- for-test, design-for-manufacturing, silicon debug, manufacturing test, system test, diagnosis, failure analysis and back to process and design improvement. At ITC, design, test, and yield professionals can confront the challenges the industry faces, and learn how these challenges are being addressed by the combined efforts of academia, design tool and equipment suppliers, designers, and test engineers.

ITC, the cornerstone of the Test Week™ event, offers a wide variety of technical activities targeted at test and design theoreticians and practitioners, including: formal paper sessions, tutorials, panel sessions, case studies, a lecture series, commercial exhibits and presentations, and a host of ancillary professional meetings.

Authors are also invited to submit a **single-page** poster proposal. Posters are a useful way of presenting late-breaking results, getting feedback on an innovative method, or participating without having to write a full paper. Acceptance as a poster does not preclude submission of a more complete treatment as an ITC paper in 2011.

Poster submission deadline: June 20, 2010
Author notification: July 8, 2010
One-page paper due: July 17, 2010

Panel organizers are invited to submit panel ideas to highlight new developments and trends in test, to invite group discussion on controversies in test approaches, or to educate the audience on new standards or practices. Submissions must describe the area and possible positions of different panelists.

For detailed information about the submission process, requirements and deadlines, the selection process and any other questions regarding the program itself or contact information, please consult the ITC web sites at <http://www.itctestweek.org>.



ITC invites submissions on the latest techniques for testing and diagnosing ICs, boards and systems.

Conference Focus Topics

Test and Design for Manufacturability
Yield Analysis & Optimization
Embedded Instruments (BIST & DFT)
Reliability Screening
Low-Cost Test
Diagnosis & Silicon Debug
High-Speed I/O and RF Test
Probe-card Design & Simulation
Self Repair & Fault tolerance
System Test & False Positives
Emerging DUTs
Experiments and Case Studies

Hot Topics

Adaptive Test
Board Test
Defect-based Testing
Innovative Industrial Test Practice
Fault Modeling & Simulation & Test
Power Issues in Test
Standalone Memory Test & Repair
ATE Hardware and Software
Online Test
Protocol Aware Test
Design Verification & Validation
Test Resource Partitioning
Test Floor Optimizations
CIS Test

Regular Topics

Automatic Test Generation
Boundary-Scan
On-Chip Test Compression
Economics of Test
FPGA Test
Online Test
I_{DDQ} and Current Test
Interface Issues
Microprocessor Test
Mixed-Signal and Analog Test
Multisite Test
System-in-Package and KGD Test
Test Standards
Test Quality & Reliability

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